



Material Content Data Sheet



Sales Product Name		BSS816NW H6327		Issued		1. August 2018		
MA#		MA001674348						
Package		PG-SOT323-3-3		Weight*		6.00 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.03		345	
	noble metal	gold	7440-57-5	0.008	0.13		1337	
	inorganic material	silicon	7440-21-3	0.122	2.04	2.20	20405	22087
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		438	
	non noble metal	chromium	7440-47-3	0.008	0.13		1315	
	non noble metal	copper	7440-50-8	2.617	43.67	43.85	436524	438365
wire	non noble metal	copper	7440-50-8	0.025	0.41	0.41	4092	4092
encapsulation	organic material	carbon black	1333-86-4	0.031	0.51		5117	
	plastics	epoxy resin	-	0.659	11.00		110005	
	inorganic material	silicondioxide	60676-86-0	2.377	39.65	51.16	396529	511651
leadfinish	non noble metal	tin	7440-31-5	0.133	2.21	2.21	22135	22135
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1670	1670
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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